

WHAT IS CLAIMED IS:

1. A method for packaging a plurality of dies, said method comprising:

5 providing a structural member comprising a base member having first and second surfaces, said base member comprising a plurality of mounting stations, each mounting station comprising a cavity wall that surrounds that mounting station and extends from said first surface thereby forming an open cavity around said mounting station;

10 attaching each die to a corresponding one of said mounting stations;

positioning a lid sheet over said structural member, said lid sheet comprising a plurality of covers for closing said cavities said covers being connected to one another by connection members;

15 placing said structural member with said positioned lid sheet in a mold with a molding compound in contact with said lid sheet, said mold having a surface that forces said covers against said cavity while forcing said molding compound between said cavity walls; and

20 causing said molding compound to solidify.

2. The method of Claim 1 wherein one of said connection members comprises a spring member that extends away from said covers and said first surface.

25 3. The method of Claim 2 wherein said mold surface is in contact with said spring member when said molding compound is forced between said cavity walls.

30 4. The method of Claim 1 wherein one of said mounting stations comprises a wire bonding pad and wherein said die is connected to said wire bonding pad when said die is attached to said mounting station.

5. The method of Claim 1 wherein one of said mounting stations comprises a die mounting pad and wherein said die is connected to said die mounting pad by a layer of adhesive when said die is attached to said mounting station.

5 6. The method of Claim 5 wherein said die mounting pad comprises a heat sink for removing heat from said die.

 7. The method of Claim 1 wherein said base member comprises a lead frame that is partially encased in a mold compound.

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